TOSHIBA DIODE SILICON EPITAXIAL SCHOTTKY BARRIER TYPE

1 S S 3 6 7

HIGH SPEED SWITCHING APPLICATION

- Small Package
- Low Forward Voltage: $V_F = 0.23V$ (TYP.) @ $I_F = 5mA$

MAXIMUM RATINGS (Ta = 25°C)

100 0 (10 - 25 C)			
CHARACTERISTIC	SYMBOL	RATING	UNIT
Maximum (Peak) Reverse Voltage	$v_{ m RM}$	15	V
Reverse Voltage	$ m v_R$	10	V
Maximum (Peak) Forward Current	$I_{ ext{FM}}$	200	mA
Average Forward Current	IO	100	mA
Surge Current (10ms)	$I_{ m FSM}$	1	A
Power Dissipation	P%	200	mW
Junction Temperature	T_{j}	125	°C
Storage Temperature Range	$\mathrm{T_{stg}}$	-55~125	°C
Operating Temperature Range	$T_{ m opr}$	-40~100	°C

Unit in mm +0.2 1.25 - 0.1 CATHODE MARK +0.20.05 $0.3 + 0.1 \\ -0.05$ 0.15 + 0.1USC **JEDEC EIAJ** 1-1E1A TOSHIBA

Weight: 0.004g

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	$V_{F(1)}$	$I_{\mathbf{F}} = 1 \text{mA}$	_	0.18	_	_
	$V_{F(2)}$	$I_{\mathbf{F}} = 5 \text{mA}$	_	0.23	0.30	V
	$V_{F(3)}$	$I_{ m F} = 100 { m mA}$	_	0.35	0.50	
Reverse Current	$I_{\mathbf{R}}$	$V_R = 10V$	_	_	20	μ A
Total Capacitance	$\mathrm{C}_{\mathbf{T}}$	V_R =0, f=1MHz	_	20	40	рF

EQUIVALENT CIRCUIT (TOP VIEW)

MARKING





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Mounted on a glass epoxy circuit board of 20×20mm Pad dimension of 4×4mm.







